



Material Content Data Sheet



Sales Product Name				BSC067N06LS3 G		Issued		9. January 2019	
MA#				MA002561744					
Package				PG-TDSON-8-14		Weight*		119.39 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	1.817	1.52	1.52	15222	15222	
leadframe	inorganic material	phosphorus	7723-14-0	0.010	0.01		81		
	non noble metal	zinc	7440-66-6	0.039	0.03		326		
	non noble metal	iron	7439-89-6	0.778	0.65		6516		
wire	non noble metal	copper	7440-50-8	31.590	26.46	27.15	264593	271516	
	non noble metal	copper	7440-50-8	0.059	0.05	0.05	495	495	
	encapsulation	organic material	carbon black	1333-86-4	0.236	0.20		1979	
	plastics	epoxy resin	-	7.324	6.13		61349		
	inorganic material	silicondioxide	60676-86-0	39.694	33.27	39.60	332471	395799	
leadfinish	non noble metal	tin	7440-31-5	1.243	1.04	1.04	10408	10408	
plating	noble metal	silver	7440-22-4	0.037	0.03	0.03	314	314	
solder	non noble metal	tin	7440-31-5	0.037	0.03		306		
	noble metal	silver	7440-22-4	0.046	0.04		383		
	non noble metal	lead	7439-92-1	1.746	1.46	1.53	14625	15314	
heatspreader	inorganic material	phosphorus	7723-14-0	0.005	0.00		45		
	non noble metal	zinc	7440-66-6	0.021	0.02		179		
	non noble metal	iron	7439-89-6	0.428	0.36		3581		
heat sink CLIP	non noble metal	copper	7440-50-8	17.360	14.54	14.92	145404	149209	
	inorganic material	phosphorus	7723-14-0	0.005	0.00		43		
	non noble metal	iron	7439-89-6	0.017	0.01		142		
	non noble metal	copper	7440-50-8	16.898	14.15	14.16	141538	141723	
*deviation	< 10%					Sum in total:	100.00	1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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